

Patent Abstracts of Japan

PUBLICATION NUMBER : 08088464  
PUBLICATION DATE : 02-04-96

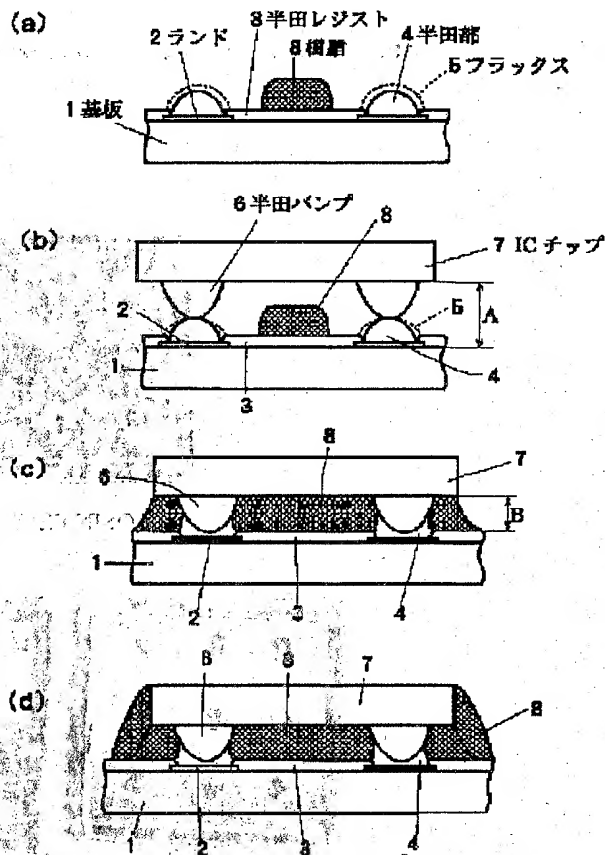
APPLICATION DATE : 20-09-94  
APPLICATION NUMBER : 06224407

APPLICANT : SONY CORP;

INVENTOR : NAKAMURA TOSHIFUMI;

INT.CL. : H05K 3/34 H05K 3/34 // H05K 1/18

TITLE : FLIP-CHIP-MOUNTING METHOD



ABSTRACT : PURPOSE: To reduce the number of processes and cost in flip-chip mounting and to improve the mounting reliability.

CONSTITUTION: A land 2 formed on a substrate 1 is covered with a solder part 4, resin 8 is applied to the surface other than the solder part 4 of the substrate 1, flux 5 is applied to the surface of the solder part 4, and then an IC chip 7 is mounted to the solder part 4, and then the soldering by heating and the filling of the resin 8 are performed simultaneously.

COPYRIGHT: (C)1996,JPO